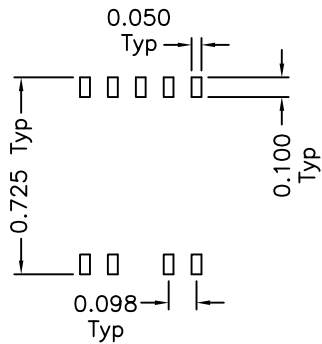
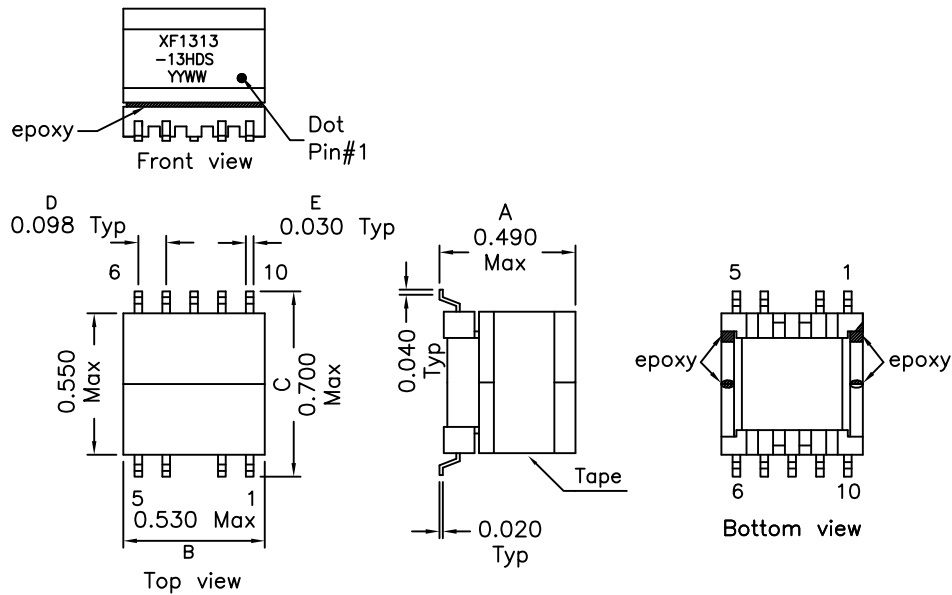


## 1. Mechanical Dimensions:



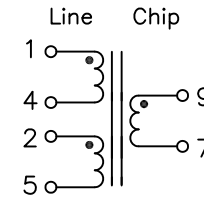
Suggested PCB Layout

### Notes:

1. Solderability: Leads shall meet MIL-STD-202G, Method 208H for solderability.
2. Flammability: UL94V-0
3. ASTM oxygen index: > 28%
4. Insulation System: Class F 155°C. UL file E151556
5. Operating Temperature Range: All listed parameters are to be within tolerance from -40°C to +85°C
6. Storage Temperature Range: -55°C to +125°C
7. Aqueous wash compatible
8. SMD Lead Coplanarity:  $\pm 0.004'' (0.102\text{mm})$
9. Electrical and mechanical specifications 100% tested
10. RoHS Compliant Component
11. Recommended IR Reflow peak temp of 235C Max.
12. Remove Pins 3
13. UL60950 R/C, Supplementary Insulation for a working voltage up to 250V, file #E165866.

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## 2. Schematic:



## 3. Electrical Specifications: @25°C

- OCL: Pins 1-5 2.0mH  $\pm 10\%$  @10KHz 0.1V  
 1.7mH Min @10KHz 0.1V 160mADC (Tie 2-4)
- Q: Pins 1-5 8 Min @10KHz 0.1V
- LL: Pins 1-5 11uH Max @100KHz 100mV (Tie 2+4, 7+9)
- URNS RATIO: (1-5):(9-7) = 2:1 $\pm 1\%$  (Tie 2+4)
- DC Res.: Pins 1-4 1.25 Ohms Max  
 Pins 2-5 1.25 Ohms Max  
 Pins 9-7 1.25 Ohms Max
- THD: -70dB Max @20KHz, 1-5(Tie 2+4)  
 1.85Vrms, 32 Ohm Load, 7-9
- ISOLATION VOLTAGE: 2500Vrms (Chip to Line)

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TOLERANCES: .xxx $\pm 0.010$	DWN.	Yuan	Sep-17-13
Dimensions in INCH	CHK.	YK Liao	Sep-17-13
SHEET 1 OF 1	APP.	Joe Huff	Sep-17-13